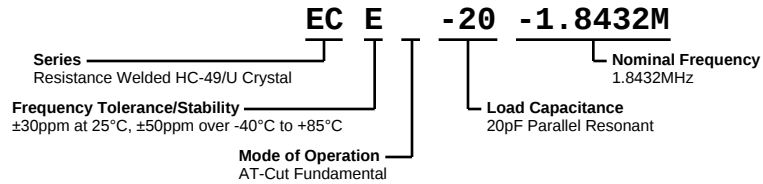


# ECE-20-1.8432M



## ELECTRICAL SPECIFICATIONS

|                               |                                                                                                               |
|-------------------------------|---------------------------------------------------------------------------------------------------------------|
| Nominal Frequency             | 1.8432MHz                                                                                                     |
| Frequency Tolerance/Stability | $\pm 30\text{ppm}$ at $25^\circ\text{C}$ , $\pm 50\text{ppm}$ over $-40^\circ\text{C}$ to $+85^\circ\text{C}$ |
| Aging at $25^\circ\text{C}$   | $\pm 5\text{ppm/year}$ Maximum                                                                                |
| Load Capacitance              | 20pF Parallel Resonant                                                                                        |
| Shunt Capacitance (C0)        | 7pF Maximum                                                                                                   |
| Equivalent Series Resistance  | 650 Ohms Maximum                                                                                              |
| Mode of Operation             | AT-Cut Fundamental                                                                                            |
| Drive Level                   | 2mWatts Maximum                                                                                               |
| Storage Temperature Range     | $-40^\circ\text{C}$ to $+85^\circ\text{C}$                                                                    |
| Insulation Resistance         | 500 Megaohms Minimum at 100Vdc                                                                                |

## ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

|                              |                                       |
|------------------------------|---------------------------------------|
| Fine Leak Test               | MIL-STD-883, Method 1014, Condition A |
| Gross Leak Test              | MIL-STD-883, Method 1014, Condition C |
| Lead Integrity               | MIL-STD-883, Method 2004              |
| Mechanical Shock             | MIL-STD-202, Method 213, Condition C  |
| Resistance to Soldering Heat | MIL-STD-202, Method 210               |
| Resistance to Solvents       | MIL-STD-202, Method 215               |
| Solderability                | MIL-STD-883, Method 2003              |
| Temperature Cycling          | MIL-STD-883, Method 1010              |
| Vibration                    | MIL-STD-883, Method 2007, Condition A |

# ECE-20-1.8432M

MECHANICAL DIMENSIONS (all dimensions in millimeters)



| LINE | MARKING                                                        |
|------|----------------------------------------------------------------|
| 1    | ECLIPTEK                                                       |
| 2    | E1.8432M<br><i>E=Ecliptek Designator or Blank (No Marking)</i> |
| 3    | XX<br><i>XX=Ecliptek Manufacturing Code</i>                    |

## Recommended Solder Reflow Methods



### High Temperature Solder Bath (Wave Solder)

|                                          |                    |
|------------------------------------------|--------------------|
| $T_S \text{ MAX to } T_L$ (Ramp-up Rate) | 3°C/second Maximum |
|------------------------------------------|--------------------|

#### Preheat

|                                             |                  |
|---------------------------------------------|------------------|
| - Temperature Minimum ( $T_S \text{ MIN}$ ) | 150°C            |
| - Temperature Typical ( $T_S \text{ TYP}$ ) | 175°C            |
| - Temperature Maximum ( $T_S \text{ MAX}$ ) | 200°C            |
| - Time ( $t_s \text{ MIN}$ )                | 60 - 180 Seconds |

|                                 |                    |
|---------------------------------|--------------------|
| Ramp-up Rate ( $T_L$ to $T_P$ ) | 3°C/second Maximum |
|---------------------------------|--------------------|

#### Time Maintained Above:

|                         |                  |
|-------------------------|------------------|
| - Temperature ( $T_L$ ) | 217°C            |
| - Time ( $t_L$ )        | 60 - 150 Seconds |

|                            |                                      |
|----------------------------|--------------------------------------|
| Peak Temperature ( $T_P$ ) | 260°C Maximum for 10 Seconds Maximum |
|----------------------------|--------------------------------------|

|                                                  |               |
|--------------------------------------------------|---------------|
| Target Peak Temperature ( $T_P \text{ Target}$ ) | 250°C +0/-5°C |
|--------------------------------------------------|---------------|

|                                          |                 |
|------------------------------------------|-----------------|
| Time within 5°C of actual peak ( $t_P$ ) | 20 - 40 seconds |
|------------------------------------------|-----------------|

|                |                    |
|----------------|--------------------|
| Ramp-down Rate | 6°C/second Maximum |
|----------------|--------------------|

|                                   |                   |
|-----------------------------------|-------------------|
| Time 25°C to Peak Temperature (t) | 8 minutes Maximum |
|-----------------------------------|-------------------|

|                            |         |
|----------------------------|---------|
| Moisture Sensitivity Level | Level 1 |
|----------------------------|---------|

## Recommended Solder Reflow Methods



### Low Temperature Solder Bath (Wave Solder)

**Ts MAX to Tl (Ramp-up Rate)** 5°C/second Maximum

#### Preheat

- Temperature Minimum (Ts MIN) N/A
- Temperature Typical (Ts TYP) 150°C
- Temperature Maximum (Ts MAX) N/A
- Time (ts MIN) 30 - 60 Seconds

**Ramp-up Rate (Tl to Tp)** 5°C/second Maximum

#### Time Maintained Above:

- Temperature (Tl) 150°C
- Time (tL) 200 Seconds Maximum

**Peak Temperature (Tp)** 245°C Maximum

**Target Peak Temperature (Tp Target)** 245°C Maximum 1 Time / 235°C Maximum 2 Times

**Time within 5°C of actual peak (tp)** 5 seconds Maximum 1 Time / 15 seconds Maximum 2 Times

**Ramp-down Rate** 5°C/second Maximum

**Time 25°C to Peak Temperature (t)** N/A

**Moisture Sensitivity Level** Level 1

### Low Temperature Manual Soldering

185°C Maximum for 10 seconds Maximum, 2 times Maximum.

### High Temperature Manual Soldering

260°C Maximum for 5 seconds Maximum, 2 times Maximum.